

HiPerFET™ Power MOSFETs Q-Class

IXFH 58N20Q
IXFT 58N20Q

V_{DSS} = 200 V
I_{D25} = 58 A
R_{DS(on)} = 40 mΩ

t_{rr} ≤ 200 ns

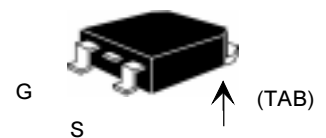
N-Channel Enhancement Mode
Avalanche Rated High dv/dt, Low Q_g

Preliminary data sheet

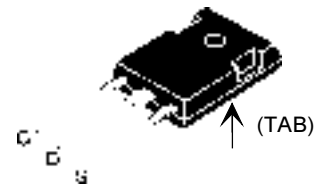


Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	200	V
V _{DGR}	T _J = 25°C to 150°C; R _{GS} = 1 MΩ	200	V
V _{GS}	Continuous	±20	V
V _{GSM}	Transient	±30	V
I _{D25}	T _C = 25°C	58	A
I _{DM}	T _C = 25°C, pulse width limited by T _{JM}	232	A
I _{AR}	T _C = 25°C	58	A
E _{AR}	T _C = 25°C	30	mJ
E _{AS}	T _C = 25°C	1.0	J
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100 A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150°C, R _G = 2 Ω	5	V/ns
P _D	T _C = 25°C	300	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	1.6 mm (0.062 in.) from case for 10 s	300	°C
M _d	Mounting torque	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

TO-268 (D3) (IXFT) Case Style



TO-247 AD



G = Gate D = Drain
S = Source TAB = Drain

Features

- IXYS advanced low Q_g process
- International standard packages
- Low gate charge and capacitance
 - easier to drive
 - faster switching
- Low R_{DS(on)}
- Unclamped Inductive Switching (UIS) rated
- Molding epoxies meet UL 94 V-0 flammability classification

Advantages

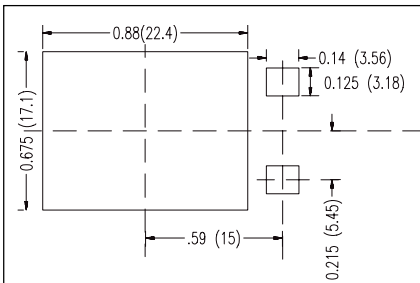
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
V _{DSS}	V _{GS} = 0 V, I _D = 250 μA	200		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 4 mA	2.0		V
I _{GSS}	V _{GS} = ±20 V _{DC} , V _{DS} = 0			±100 nA
I _{DSS}	V _{DS} = V _{DSS} , T _J = 25°C			25 μA
	V _{GS} = 0 V, T _J = 125°C			1 mA
R _{DS(on)}	V _{GS} = 10 V, I _D = 0.5 I _{D25} Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			40 mΩ

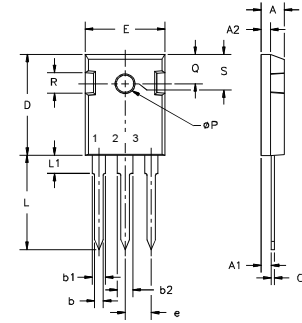
Symbol	Test Conditions	Characteristic Values			
		(T _J = 25°C, unless otherwise specified)			
		Min.	Typ.	Max.	
g_{fs}	V _{DS} = 10 V; I _D = 0.5 I _{D25} , pulse test	24	34	S	
C_{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		3600	pF	
C_{oss}			870	pF	
C_{rss}			280	pF	
t_{d(on)}	V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25} R _G = 1.5 Ω (External)		20	ns	
t_r			40	ns	
t_{d(off)}			40	ns	
t_f			13	ns	
Q_{g(on)}	V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25}		98	140	nC
Q_{gs}			25	35	nC
Q_{gd}			45	70	nC
R_{thJC}	(TO-247)		0.25	0.42	KW
R_{thCK}				KW	

Symbol	Test Conditions	Characteristic Values			
		(T _J = 25°C, unless otherwise specified)			
		min.	typ.	max.	
I_S	V _{GS} = 0 V			58	A
I_{SM}	Repetitive;			232	A
V_{SD}	I _F = I _S , V _{GS} = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			1.5	V
t_{rr}	I _F = I _S -di/dt = 100 A/μs, V _R = 100 V		0.7	200	ns
Q_{RM}				7	μC
I_{RM}					A

Min. Recommended Footprint
Dimensions in mm and inches



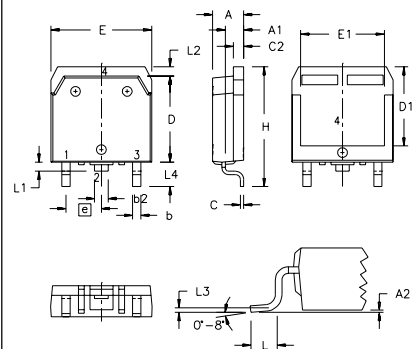
TO-247 AD Outline



Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L ₁		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

TO-268 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025